

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6860617

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	YASUYUKI SAKOGAWA	08/06/2021
RECEIVING PARTY DATA		
Name:	MICRON TECHNOLOGY, INC.	
Street Address:	8000 SOUTH FEDERAL WAY	
City:	BOISE	
State/Country:	IDAHO	
Postal Code:	83716-9632	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	17400002	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
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ATTORNEY DOCKET NUMBER:	P293179US01	
NAME OF SUBMITTER:	DENISE SHERIDAN	
SIGNATURE:	/Denise Sheridan/	
DATE SIGNED:	08/11/2021	
Total Attachments: 2		
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Yasuyuki Sakogawa

Filed : Concurrently herewith

For : SEMICONDUCTOR DEVICE AND
METHOD FOR FORMING THE WIRING
STRUCTURES AVOIDING SHORT CIRCUIT
THEREOF

Docket No. P293179.US.01

Disclosure No. 2021-134991-US

ASSIGNMENT :

☒ Enclosed for recording

☐ Previously recorded

Date: _____

Reel: _____

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned do hereby:

SELL, ASSIGN AND TRANSFER to **Micron Technology, Inc.** (the "Assignee"), a corporation of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83716-9632, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled "**SEMICONDUCTOR DEVICE AND METHOD FOR FORMING THE WIRING STRUCTURES AVOIDING SHORT CIRCUIT THEREOF**"; such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT that, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such improvements; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such improvements and the history thereof; and generally do everything possible which the Assignee shall consider desirable for securing, maintaining and enforcing proper patent protection for such improvements and for vesting title to such improvements in the Assignee;

TO BE BINDING on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

Signature: Yasuyuki Sakogawa

Date: 2021-08-06
(YYYY-MM-DD)

Assignor Name: Yasuyuki Sakogawa